ZH05 SERIES

Electroformed Bond Hub Blades

Print 🖶

Provides stable processing through high-accuracy concentration control

Electroformed bond

Applications: Silicon wafer, Compound semiconductor wafers (GaAs, GaP, etc.), Oxide wafers (LiTaO₃, etc.), etc

Newly developed grit concentration control technology has made possible five distinct levels of grit concentration. This wider range of choices offers improved balance between blade life and process quality (in particular, backside chipping).

- 5 grit concentration levels support diverse applications.
- The ZH05 Series offers shorter precut times and lower chance of blade breakage due to flying die.

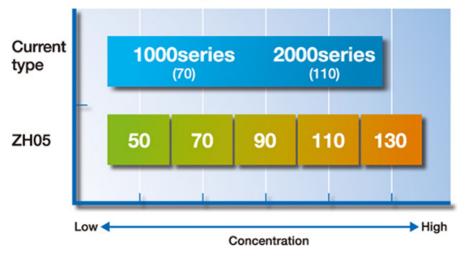


Concentration range

During dicing, concentration affects both the speed of blade wear and the size of chipping. By selecting precisely a concentration* that is appropriate to the application, both wear speed and process quality can be made more stable and consistent.

*Concentration refers to the percentage of diamond grit in the abrasive portion of the blade. For example, a concentration level of 100 indicates 25 % diamond grit by volume.

Concentration range

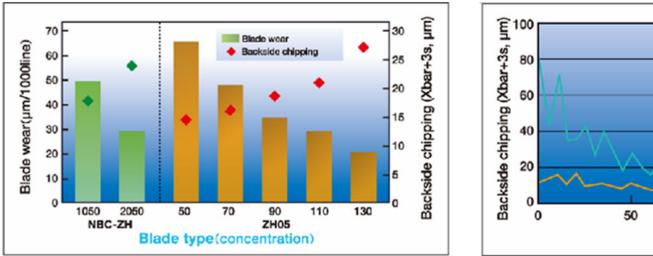


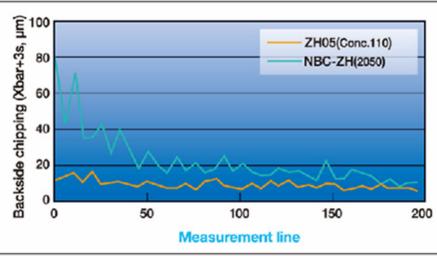
Experimental Data

By increasing the concentration options for ZH05, it is possible to precisely respond to customer needs. It also has the potential to shorten the precut time.

Relationship between Wheel Wear and Backside Chipping

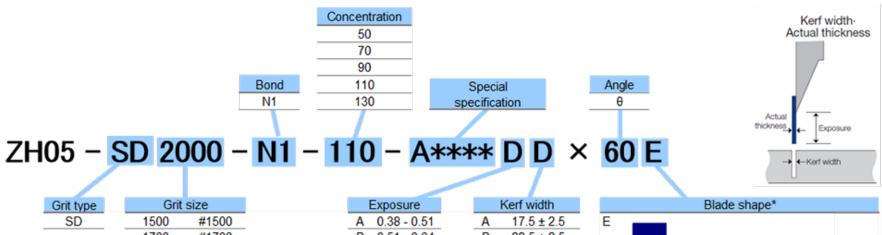
Precut Reduction Effect





Workpiece	:Φ6" Si+Oxide layer	Workpiece	:Ф6" Si
Depth	:400 μm (full cut)	Depth	:400 µm (full cut)
Feed speed	:60 mm/s	Feed speed	:10, 20, 30 mm/s (each of 10lines)
Spindle revolution	:30,000 min ⁻¹		40, 50 mm/s(each of 20lines) 60 mm/s(each of 130lines)
		Spindle revolution	:30,000 min ⁻¹

Specification



Grit type	Grit	size	Exposure	ł	Kerf width			Blade sha	ape*		
SD	1500	#1500	A 0.38 - 0.51	Α	17.5 ± 2.5	E					
	1700	#1700	B 0.51 - 0.64	В	22.5 ± 2.5						
	1800	#1800	C 0.64 - 0.76	С	27.5 ± 2.5		<u> </u>				
	2000	#2000	D 0.76 - 0.89	D	32.5 ± 2.5	N					
	2500	#2500	E 0.89 - 1.02	E	37.5 ± 2.5						
	3000	#3000	F 1.02 - 1.15	F	45.0 ± 5.0		7.0				
	3500	#3500	G 1.15 - 1.28	G	55.0 ± 5.0	М		MA		MB	
	4000	#4000	H 1.28 - 1.41	н	65.0 ± 5.0				/		
	4500	#4500	1 1 41 - 1 54	1	750+50		$\wedge \theta$				